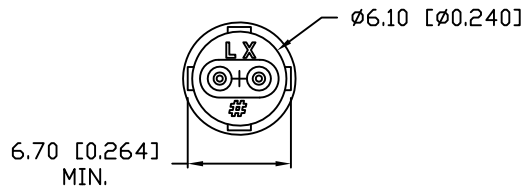
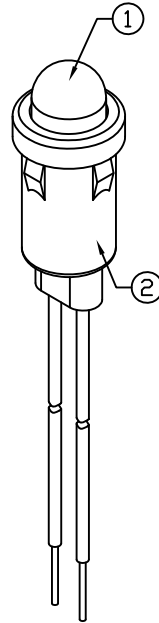
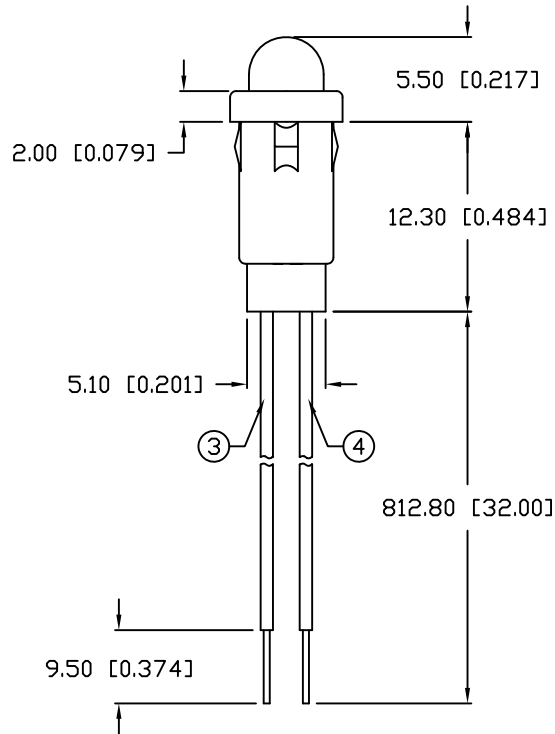
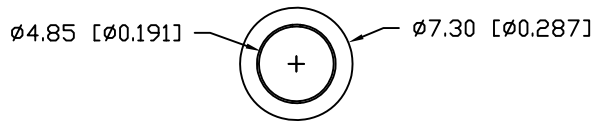


PART NUMBER		REV.
SSI-LXH600YD-813		—
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE



PANEL HOLE: 0.250"  
PANEL THICKNESS: 0.030" MIN.

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>r</sub> =100μA
AXIAL INTENSITY		30		mcd	I <sub>f</sub> =20mA
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

\* t<10μS

NOTES:

- SSL-LX509F3YD LED.
- SSH-LXH600 HOLDER, BLACK.
- ANODE LEAD: LXP-WST24RDT0C, 24 AWG STRANDED, TOP OVERCOAT, RED INSULATION, CUT 825mm LONG, STRIP 4mm & 9.5mm.
- CATHODE LEAD: LXP-WST24BLT0C, 24 AWG STRANDED, TOP OVERCOAT, BLACK INSULATION, CUT 825mm LONG, STRIP 4mm & 9.5mm.

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER
—	SSI-LXH600YD-813

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T-5mm (T-1 3/4) LED, PANEL MOUNT INDICATOR,  
585nm YELLOW LED, YELLOW DIFFUSED LENS.  
WITH 32" WIRE LEADS.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 05.03.13
MA			PAGE: 1 OF 1
			SCALE: N/A